

I claim:

1. A method of making an IC package mold lock comprising the steps of:
 providing a first niche in a leadframe surface;
 providing an opposing niche in an opposing leadframe surface, the opposing niche partially intersecting with the first niche such that an aperture in the leadframe is defined by the intersecting portions, and such that a key is defined by the nonintersecting portions; and
 encapsulating the key with mold compound to form a mold lock.
2. The method of claim 1 wherein the encapsulating step further comprises filling the first niche, opposing niche, and aperture with mold compound.
3. The method of claim 1 wherein the providing steps further comprise the steps of masking and etching the leadframe surfaces.
4. The method of claim 1 wherein the step of providing an opposing niche further comprises the step of providing an opposing niche axially unaligned with a first niche of approximately identical same size and shape.
5. The method of claim 1 wherein the step of providing an opposing niche further comprises the step of providing an opposing niche axially aligned with a first niche of nonidentical size and shape.
6. The method of claim 1 wherein the leadframe surfaces further comprise lead finger surfaces.
7. The method of claim 1 wherein the leadframe surfaces further comprise die pad surfaces.

8. An IC package mold lock comprising:
a leadframe having an aperture, the aperture having a key; and
mold compound disposed in the aperture and encapsulating the key for
forming a mold lock.
9. An IC package mold lock according to claim 8 wherein the aperture is
disposed in a lead finger of the leadframe.
10. An IC package mold lock according to claim 8 wherein the aperture is
disposed in a die pad of the leadframe.
11. An IC package mold lock according to claim 8 wherein the IC package
further comprises a QFN package.
12. An IC package mold lock according to claim 8 wherein the IC package
further comprises a DIP package.
13. An IC package mold lock according to claim 8 wherein the mold compound
fills the aperture.
14. An IC package mold lock according to claim 8 wherein the key further
comprises a first niche in a surface of the leadframe axially unaligned with a
partially intersecting opposing niche in an opposing surface of the leadframe, the
niches being of approximately identical same size and shape.
15. An IC package mold lock according to claim 8 wherein the key further
comprises a first niche in a surface of the leadframe axially aligned with a
partially intersecting opposing niche in an opposing surface of the leadframe, the
niches being of nonidentical size and shape.

16. An IC package comprising:
 - a leadframe having a die pad and a plurality of lead fingers;
 - a plurality of apertures in the leadframe, at least one of the apertures having a key; and
 - mold compound encapsulating the key forming a mold lock.
17. An IC package according to claim 16 wherein the at least one aperture having a key is disposed in a lead finger of the leadframe.
18. An IC package according to claim 16 wherein the at least one aperture having a key is disposed in a die pad of the leadframe.
19. An IC package according to claim 16 wherein the IC package further comprises a QFN package.
20. An IC package according to claim 16 wherein the IC package further comprises a DIP package.
21. An IC package according to claim 16 wherein the mold compound fills the at least one aperture.
22. An IC package according to claim 16 wherein the at least one aperture having a key further comprises a first niche in a surface of the leadframe axially unaligned with a partially intersecting opposing niche in an opposing surface of the leadframe, the niches being of approximately identical same size and shape.
23. An IC package according to claim 16 wherein the at least one aperture having a key further comprises a first niche in a surface of the leadframe axially aligned with a partially intersecting opposing niche in an opposing surface of the leadframe, the niches being of nonidentical size and shape.